

## Lonten N-channel 30V, 5.8A, 26mΩ Power MOSFET

#### **Description**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

#### **Features**

- $30V,5.8A,R_{DS(ON).max}=26m\Omega@V_{GS}=10V$
- ♦ Improved dv/dt capability
- ♦ Fast switching
- Green device available

### **Applications**

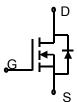
- PWM application
- Load switch
- Power management

#### **Product Summary**

 $\begin{array}{ll} V_{DSS} & 30V \\ R_{DS(on).max} \textcircled{0} \ V_{GS} \text{=} 10V & 26m\Omega \\ I_D & 5.8A \end{array}$ 

#### **Pin Configuration**





N-Channel MOSFET



## Absolute Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	30	V
Continuous drain current ( T <sub>A</sub> = 25°C )	lo -	5.8	A
Continuous drain current ( T <sub>A</sub> = 100°C )		3.7	A
Pulsed drain current <sup>1)</sup>	І <sub>ОМ</sub>	23.2	Α
Gate-Source voltage	V <sub>GSS</sub>	±12	V
Power Dissipation ( T <sub>A</sub> = 25°C )	P <sub>D</sub>	1.4	W
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	°C
Operating Junction Temperature Range	TJ	-55 to +150	°C

#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	89	°C/W



Package Marking and Ordering Information

Device	Device Package	Marking
LNSA3400	SOT-23-3	3400

ss otherwise noted
ss oth

Parameter	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Static characteristics				•		
Drain-source breakdown voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0 V, I <sub>D</sub> =250uA	30			V
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	0.65	1.0	1.35	V
		V <sub>DS</sub> =30 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 25°C			1	μA
Drain-source leakage current	I <sub>DSS</sub>	V <sub>DS</sub> =24 V, V <sub>GS</sub> =0 V, T <sub>J</sub> = 125°C			10	μA
Gate leakage current, Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =12 V, V <sub>DS</sub> =0 V			100	nA
Gate leakage current, Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-12 V, V <sub>DS</sub> =0 V			-100	nA
		V <sub>GS</sub> =10 V, I <sub>D</sub> =5.8 A		18	26	mΩ
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5 V, I <sub>D</sub> =5 A		20	32	mΩ
		Vgs=2.5V, Id=4A		31	52	mΩ
Forward transconductance	<b>G</b> fs	V <sub>DS</sub> =5 V , I <sub>D</sub> =5.8A		30		S
Dynamic characteristics	'			•		
Input capacitance	C <sub>iss</sub>			494		
Output capacitance	Coss	V <sub>DS</sub> = 15 V, V <sub>GS</sub> = 0 V, F = 1MHz		62.4		pF
Reverse transfer capacitance	C <sub>rss</sub>			53.7		
Gate resistance	Rg	V <sub>GS</sub> =0V,V <sub>DS</sub> =0V,f=1MHz		4.2		mΩ
Turn-on delay time	t <sub>d(on)</sub>			7.6		
Rise time	t <sub>r</sub>	V <sub>DD</sub> = 15V,V <sub>GS</sub> =10V, I <sub>D</sub> =5.8 A,		113.2		ne
Turn-off delay time	t <sub>d(off)</sub>	Rg=10Ω		44.4		ns
Fall time	tf			13.6		
Gate charge characteristics						1
Gate to source charge	Q <sub>gs</sub>			3.3		
Gate to drain charge	Q <sub>gd</sub>	$V_{DS}$ =15V, $I_{D}$ =5.8A, $V_{GS}$ = 10V		2.1		nC
Gate charge total	Qg	- VGS- 10V		13.6		
Drain-Source diode characteris	tics and Maxi	mum Ratings				1
Continuous Source Current	Is				5.8	А
Pulsed Source Current <sup>2)</sup>	Ism	]			23.2	А
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =5.8A, T <sub>J</sub> =25℃			1.2	V
				1	1	1

### Notes:

<sup>1:</sup> Repetitive Rating: Pulse width limited by maximum junction temperature.

<sup>2:</sup> Pulse Test: Pulse Width  $\leq 300 \mu s$ , Duty Cycle  $\leq 2\%$ .



## **Electrical Characteristics Diagrams**

Figure 1. Typ. Output Characteristics

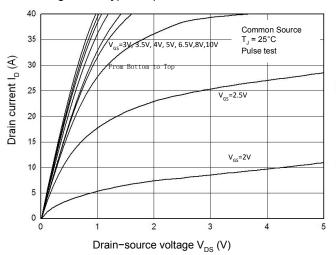


Figure 2. Transfer Characteristics

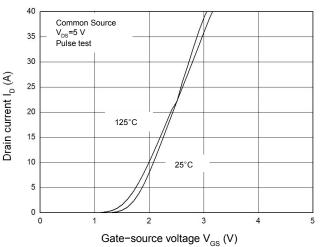


Figure 3. Capacitance Characteristics

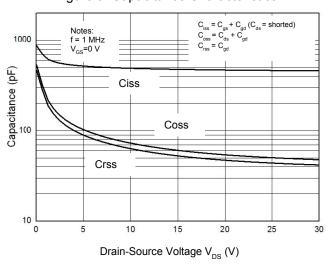


Figure 4. Gate Charge Waveform

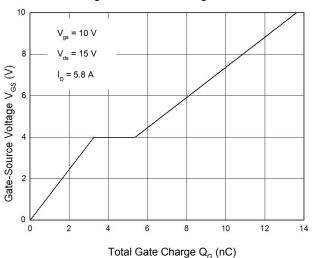


Figure 5. Body-Diode Characteristics

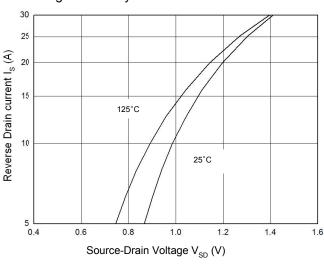


Figure 6. Rdson-Drain Current

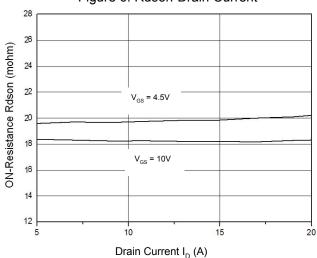




Figure 7. Rdson-Junction Temperature(℃)

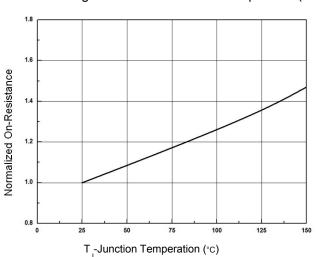


Figure 8. Maximum Safe Operating Area

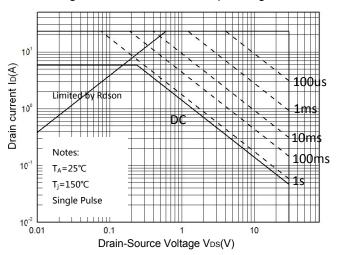
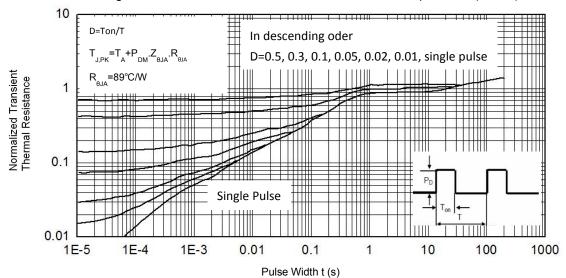


Figure 9. Normalized Maximum Transient Thermal Impedance (RthJA)

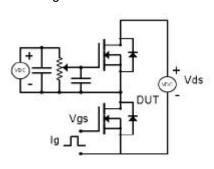


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## **Test Circuit & Waveform**

Figure 8. Gate Charge Test Circuit & Waveform



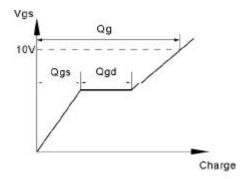
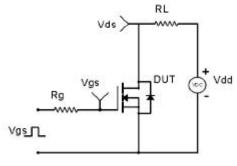


Figure 9. Resistive Switching Test Circuit & Waveforms



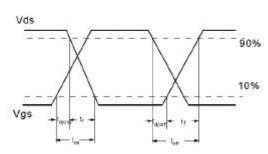
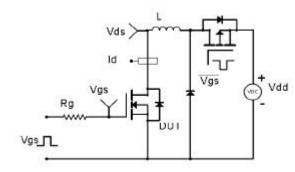


Figure 10. Unclamped Inductive Switching (UIS) Test Circuit & Waveform



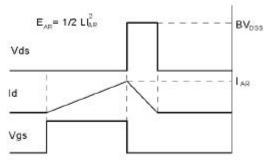
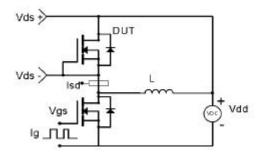
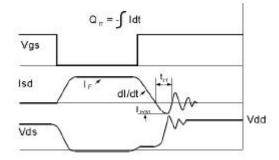


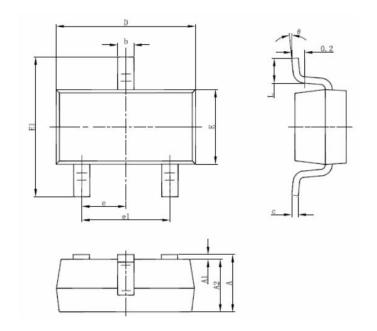
Figure 11. Diode Recovery Circuit & Waveform





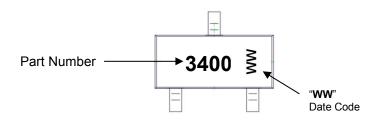


# **Mechanical Dimensions for SOT-23-3**



COMMON DIMENSIONS					
SYMBOL	MILLIME	ETERS	INCHS		
STIVIBUL	MIN	MAX	MIN	MAX	
Α	1.00	1.30	0.039	0.051	
A1	0.00	0.10	0.000	0.004	
A2	1.00	1.20	0.039	0.047	
b	0.30	0.50	0.012	0.020	
С	0.04	0.21	0.002	0.008	
D	2.80	3.00	0.110	0.118	
E	1.50	1.70	0.059	0.067	
E1	2.60	3.00	0.102	0.118	
е	0.95 TYP.		0.037 TYP.		
e1	1.90 TYP.		0.075 TYP.		
L	0.25	0.55	0.010	0.022	
θ	0°	8°	0°	8°	

## **SOT-23-3 Part Marking Information**





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